

Electronic Patent Application Fee Transmittal

Application Number:	10789258			
Filing Date:	26-Feb-2004			
Title of Invention:	DIE ATTACH PAD FOR USE IN SEMICONDUCTOR MANUFACTURING AND METHOD OF MAKING SAME			
First Named Inventor/Applicant Name:	Jaime Bayan			
Filer:	Francis Theodor Kalinski II/Sue Funchess			
Attorney Docket Number:	NSC1P295/P05886			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1400	1400
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Printed copy of patent - no color	8001	6	3	18
Total in USD (\$)				1418